ACM/IEEE INTERNATIONAL SYMPOSIUM ON LOW POWER ELECTRONICS AND DESIGN

18th International Low Power Design Contest

Hyatt Regency Bellevue, Washington, USA July 23 – 25, 2018 www.islped.org

Submission deadline: 11:59PM Pacific Standard Time, May 4th, 2018.

The International Symposium on Low Power Electronics and Design (ISLPED) is holding the International Low Power Design Contest to provide a forum for universities to showcase original "power-aware" designs and to highlight the design innovations targeting power efficiency improvement. The goal is to encourage and highlight design-oriented approaches for power reduction.

The best designs will be selected and invited for presentations at ISLPED 2018. A special session in the symposium will be devoted to the Low Power Design Contest.

Selected designs are invited to join the on-site final contest. Those candidates can apply for travel grants, and get 50% discounted registration fee (However, at least one full registration is still required for an ISLPED regular paper). **An industry-sponsored cash award will be awarded to the final winners** by the design contest selection committee based on the on-site demonstration and presentation.

The deadline for submissions is 11:59PM Pacific Standard Time, May 4th, 2018. (1) The manuscript (without a cover page, see the submission guideline) should be submitted electronically via the ISLPED submission website, and a cover page (In a separate PDF file) should be submitted to the design contest chairs via email. Acceptance and rejection notices will be emailed to the contact author by June 10, 2018.

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CONTEST SUBMISSION GUIDELINES

- Submissions of original designs developed at universities by students and faculty members are invited. Designs submitted to previous ISLPED Design Contests are not eligible. Submitted designs should not have received any awards in other contests. Designs related to the regular papers submitted to ISLPED 2018 or published in other conferences after January 1, 2017 are also welcomed. In such a case, the authors need to explicitly state that they have submitted a regular paper or their papers are accepted in other conferences in the cover page.
- Each submission **should include a cover page** in a separate PDF file including:
 - 1. Name, affiliation and address of each author;
 - A designated presenter, should the entry be accepted;
 - 3. A statement on whether a related paper was also submitted to this year's ISLPED as a regular submission or was published before;
 - 4. The following statement: "All appropriate organizational approvals for the publication of this paper have been obtained. If accepted, the author(s) will select a speaker to present and demo the design at the Symposium."
 - 5. Correspondent author, including his/her telephone number, fax number, email address, and **his/her signature**.

The cover page needs to be sent to the email address of Design Contest chair/cochair. A template of cover page will be provided on ISLPED website.

- Submissions may contain but not limited proof-of-implementation in the form of silicon chip, board or system photographs and software etc. An entry purely focusing on optimization techniques/algorithms/tools/simulations is not suitable for the contest. The submission should clarify the originality, distinguishing features, and the measured performance metrics of the design. The power targets of the design, the design choices related to power, and the specific optimizations, techniques and tradeoffs used to reduce power need to be highlighted.
- Selected design entries will be presented at the Symposium in a special session and as posters. On-site demonstrations are mandatory and the final design contest award will be selected based on the demonstration and presentation. Selected entries will not be published in the ISLPED conference proceedings and the authors can resubmit the related papers to other conferences.